IN THE CLAIMS:

1. (Original) An assembly comprising:

a substrate,

an integrated circuit device adapted to be electrically and mechanically connected to the substrate,

electrical connection pads on the integrated circuit device and on the substrate adapted to contact one another when the circuit device and the substrate are connected,

said connection pads comprising at least one first projection on one of the device and the substrate and at least two second projections on the other of the device and the substrate, each projection having a respective axial length extending from an external surface of a respective connection pad,

the at least one first projection and at least two second projections having respective external surfaces that are sized and shaped for a close friction fit along their axial lengths when interdigitated relative to one another thereby to create an axial contact area between respective projections to establish an electrical and mechanical connection between the device and the substrate.

2. (Original) An assembly as set forth in claim 1 wherein said at least one first projection is on the integrated circuit device and said at least two second projections are on the substrate.

3. (Original) An assembly as set forth in claim 1 wherein said at least one first projection comprises a headless projection.

4. (Original) An assembly as set forth in claim 1 wherein said at least one first projection comprises a solid cylindrical body.

5. (Original) An assembly as set forth in claim 1 wherein said at least one first projection is substantially rigid.

6. (Original) An assembly as set forth in claim 4 wherein said body is formed integral with said one of the circuit device or substrate.

7. (Original) An assembly as set forth in claim 6 wherein said body comprises a metal external surface for contacting said at least two second projections.

8. (Original) An assembly as set forth in claim 4 wherein said at least two second projections comprise solid cylindrical bodies and are spaced apart to form an open space for receiving said at least one first projection.

9. (Original) An assembly as set forth in claim 8 wherein said solid cylindrical bodies of the first and second projections are substantially rigid.

10. (Original) An assembly as set forth in claim 8 wherein said second projections have metal external surfaces for contact with said body of the at least one first projection.

11. (Original) An assembly as set forth in claim 1 wherein said at least one first projection comprises a frustum-shaped body.

12. (Original) An assembly as set forth in claim 1 wherein said at least one first projection and said at least two second projections have elliptical cross-sections.

13. (Original) An assembly as set forth in claim 1 wherein said at least one first projection and said plurality of second projections have polygonal cross-sections.

14. (Original) An assembly as set forth in claim 1 wherein said integrated circuit device is a MEMS device.

15. (Original) An assembly as set forth in claim 1 wherein said integrated circuit device is an optical MEMS device.

16. (Original) An assembly as set forth in claim 1 wherein said substrate is a chip carrier platform.

17. (Original) An assembly as set forth in claim 1 wherein said substrate is a circuit board.

18. (Original) An assembly comprising:

a substrate having a plurality of connection pads, each pad comprising a plurality of spaced apart electrically conductive substrate projections extending from an external surface of the pads and forming an open space therebetween, each substrate projection having a respective axial length,

an integrated circuit device adapted to be electrically and mechanically connected to the substrate, said device having a plurality of connection pads, each pad comprising at least one electrically conductive device projection extending from an external surface of the pad, each device projection having a respective axial length and being adapted for insertion into said open space such that the device and the substrate are held in

electrical and mechanical connection by a friction fit between respective axial lengths of the substrate and device projections.

19. (Original) An assembly as set forth in claim 18 wherein at least one of said substrate and device projections comprises a solid cylindrical body having a metal external surface.

20. (Original) An assembly as set forth in claim 18 wherein at least one of said substrate and device projections comprises a frustum-shaped body.

21. (Original) An assembly as set forth in claim 20 wherein said frustum-shaped body comprises a head portion adapted for insertion into said open space between substrate projections.

22. (Original) An assembly as set forth in claim 18 wherein at least one of said substrate and device projections has an elliptical cross-section.

23. (Original) An assembly as set forth in claim 18 wherein at least one of said substrate and device projections has a polygonal cross-section.

24. (Original) An assembly comprising:

a substrate,

an electrical circuit device adapted to be electrically and mechanically connected to the substrate,

a first connection pad on the substrate comprising a first set of two or more electrically conductive connecting elements protruding from an external surface of one pad, each connecting element of the first set having an axial length generally perpendicular to the substrate,

a second connection pad on the circuit device comprising a second set of one or more electrically conductive connecting elements protruding from an external surface of the pad and adapted for interdigitation with the connecting elements of the first set of connecting elements, each connecting element of the second set having an axial length,

said first and second sets of connecting elements having respective external surfaces that are sized and shaped for a close friction fit along their axial lengths when interdigitated relative to one another thereby to create an axial contact area between respective projections to establish an electrical and mechanical connection between said device and the substrate.

25. (Original) An assembly as set forth in claim 24 wherein said second set of electrically conductive connecting elements comprises a solid cylindrical body having a metal external surface.

26. (Original) An assembly as set forth in claim 24 wherein said second set of electrically conductive connecting elements comprises a frustum-shaped body extending from the second connection pad.

27. (Original) An assembly as set forth in claim 24 wherein said second set of electrically conductive connecting elements have elliptical cross-sections.

28. (Original) An assembly as set forth in claim 24 wherein said second set of electrically conductive connecting elements have polygonal cross-sections.

Claims 29-58. (Cancelled)